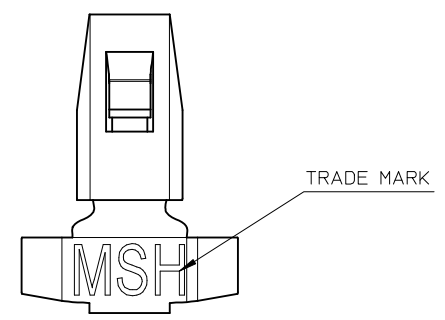
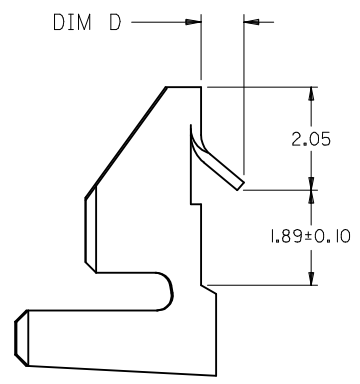
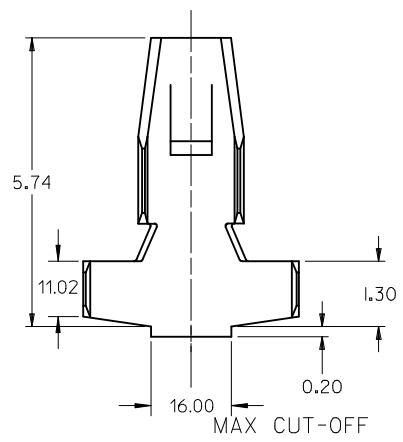


STATUS	P. N.	FORM	PCB THICKNESS	PCB $\phi$	DIM D
TOOLED	87003-9000	REEL	1.57±0.2	1.95±0.1	0.85±0.1
UNTOOLED	87003-9100	LOOSE			
UNTOOLED	87003-9200	REEL	1.20±0.2	1.85±0.05	0.75±0.1
UNTOOLED	87003-9300	LOOSE			

- NOTES:
1. MATERIAL : PRE-TIN BRASS
  2. INSERTION FORCE FOR PC HOLE TO BE 2 KG MAX.
  3. RETENTION FORCE TO PC BOARD TO BE 0.5 KG MIN.
  4. INTENDED FOR USE WITH PCB THICKNESS & PC HOLE PER CHART.
  5. WIRE RANGE: 18 ~22 AWG.
  6. INSULATION RANGE:  $\phi$ 1.7 ~  $\phi$ 3.05 MM.



REVISED EC NO: SH2009-0453 DRW:NEZHAO CHKD: APPR:HWANG	2009/01/08 2009/01/09 2009/02/25	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± 0.25 ± --- ANGULAR ± 3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			▼=0 □=0		MM ONLY	10:1	METRIC	□
			DRAWN BY JENNIFER CHECKED BY DATE 1987/11/27		TITLE	LOW PROFILE BOARD-IN CRIMP PIN		
			APPROVED BY DATE MATERIAL NO. 87003-9*00		MOLEX INCORPORATED DOCUMENT NO. SDE-87003-9*00	SHEET NO. 1 OF 1		